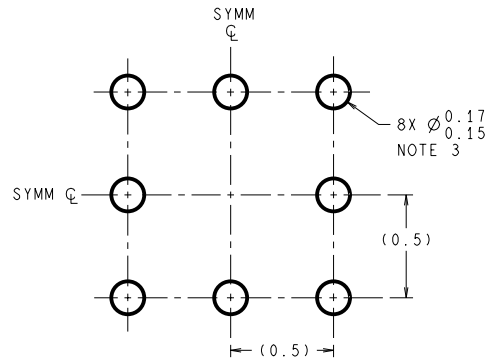
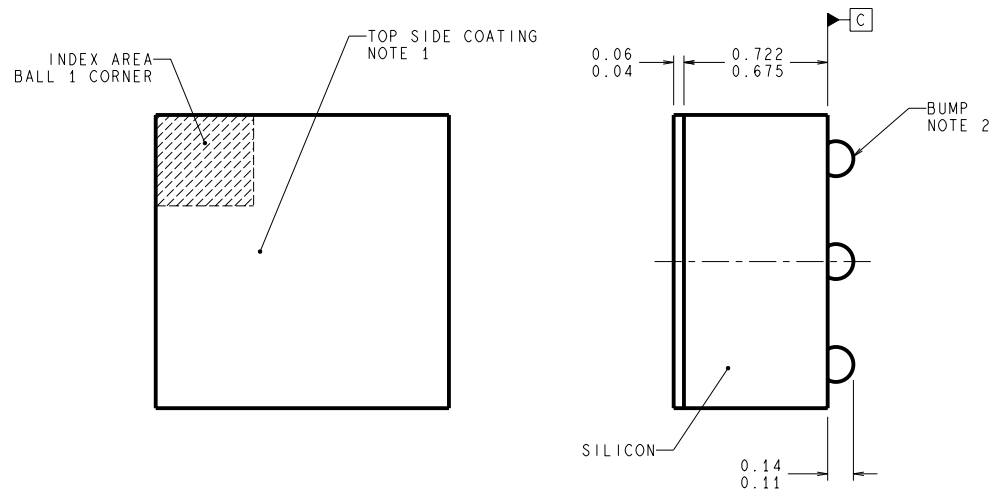


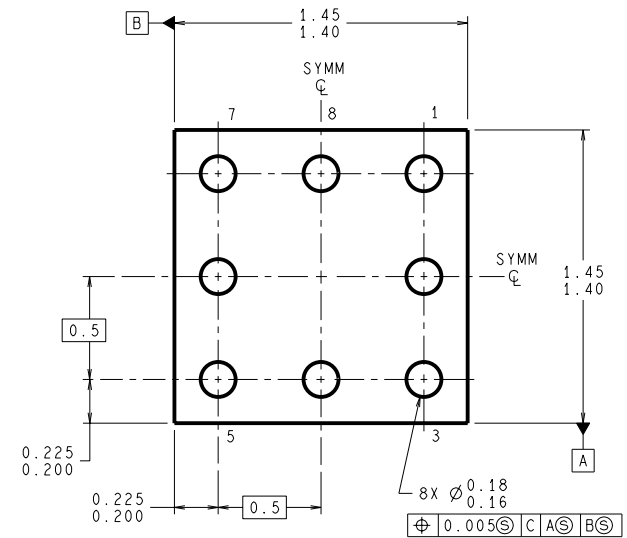
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11937	02/23/1998	MS/TK
B	REVISE PIN NUMBERS; ADD INDEX AREA; POS. TOL. WAS 0.001	12014	06/10/1998	TL/DS
C	UPDATE NOTE 4 (JEDEC REGISTRATION).	12077	08/13/1998	MS/



LAND PATTERN RECOMMENDATION



DIMENSIONS ARE IN MILLIMETERS



NOTES: UNLESS OTHERWISE SPECIFIED

1. EPOXY COATING.
2. 63Sn/Pb EUTECTIC BUMP.
3. RECOMMEND NON-SOLDER MASK DEFINED LANDING PAD.
4. REFERENCE JEDEC REGISTRATION MO-211, VARIATION BC.

APPROVALS		DATE		
DRAWN	MARTA SUCHY	02/23/1998		
DFTG. CHK.			2900 Semiconductor dr., Santa Clara, CA 95052-8090 CSP, WAFER LEVEL, 8 BUMP, 1.4 X 1.4 X 0.75mm BODY, 0.5mm PITCH	
ENGR. CHK.				
			SCALE	SIZE
			N/A	C
			DRAWING NUMBER	REV
			(SC)MKT-SWA08A	C
			DO NOT SCALE DRAWING	
			SHEET 1 of 1	